TOSHIBA TLP836

TOSHIBA PHOTOINTERRUPTER INFRARED LED + PHOTOTRANSISTOR

TLP836

STILL CAMERA

VIDEO CAMERA

FLOPPY DISK DRIVE

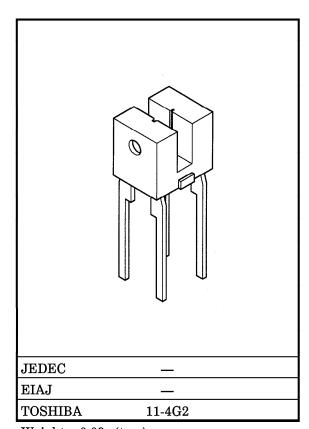
SMALL-SIZED PERSONAL OA EQUIPMENT

TLP836 is a photointerrupter consisting of a GaAs infrared LED and an Si phototransistor. It has a narrow slit and a high resolution.

- Very small package
- Printed circuit board direct mounting type
- Gap : 1mm
- High resolution:

slit width \dots 0.15mm (infrared LED side)

0.1mm (phototransistor side)



Weight: 0.09g (typ.)

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
LED	Forward Current	$I_{\mathbf{F}}$	50	mA	
	Forward Current Derating (Ta>25°C)	ΔI _F /°C	-0.67	mA/°C	
	Reverse Voltage	V_{R}	5	V	
~	Collector-Emitter Voltage	v_{CEO}	35	V	
,0E	Emitter-Collector Voltage	v_{ECO}	5	V	
CI	Collector Power Dissipation	PC	75	mW	
DETECTOR	Collector Power Dissipation Derating (Ta>25°C)	$\Delta P_{\mathbf{C}} / {^{\circ}\mathbf{C}}$	-1	mW/°C	
	Collector Current	$I_{\mathbf{C}}$	20	mA	
Operating Temperature Range		$T_{ m opr}$	-25~85	°C	
Storage Temperature Range		$\mathrm{T_{stg}}$	-40~100	°C	
Soldering Temperature (5s, Note 1)		$T_{ m sol}$	260	°C	

Note 1: At the location of 1.5mm from the resin package bottom

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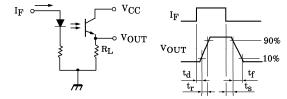
RECOMMENDED OPERATING CONDITIONS

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	v_{CC}	_	_	24	V
Forward Current	${f I_F}$			20	mA

OPTO-ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
LED	Forward Voltage		$ m v_{f F}$	$I_{\mathbf{F}} = 10 \text{mA}$	1.00	1.15	1.30	V
	Reverse Current		$I_{\mathbf{R}}$	$V_R = 5V$	_	_	10	μ A
	Peak Emission Wavelength		$\lambda_{\mathbf{P}}$	$I_{ m F} = 10 { m mA}$	_	940	_	nm
DETECTOR	Dark Current		I _D (I _{CEO})	V _{CE} =24V	_	_	0.1	μ A
	Peak Sensitivity Wavelength		$\lambda_{\mathbf{P}}$	_	_	800	_	nm
COUPLED	Current Trans	fer Ratio	$I_{\mathbf{C}}/I_{\mathbf{F}}$	$V_{CE}=5V, I_F=10mA$	0.27	1.2	_	%
	Collector-Emitter Saturation Voltage		V _{CE} (sat)	I_F =20mA, I_C =27 μ A	_	_	0.4	V
	Switching	Rise Time	$\mathfrak{t}_{\mathbf{r}}$	$V_{CC}=5V, I_C=2mA$	_	4	_	
	Time	Fall Time	t_f	$R_L = 100\Omega$ (Note 2)	_	5		μ s

Note 2: Switching time measurement circuit and waveform



PRECAUTIONS

- When removing flux with chemicals after soldering, clean only the leads on the soldering side; do not dip the whole package for cleaning.
 - Chemicals remaining on an LED or photo transistor light emitter or receiver, if any, would have a bad influence to the optical characteristics and it may severely lower the conversion efficiency.
- The environment to install the device should be determined carefully. Oil or chemicals may cause the package to be dissolved or cracked.
- The device should be mounted on an unwarped surface.
- The current transfer ratio is gradually lowered when infrared LED is powered. The efficiency deterioration by aging should be considered when designing the circuit.
- Stress causing the package deformation or deterioration should not be given to the package.

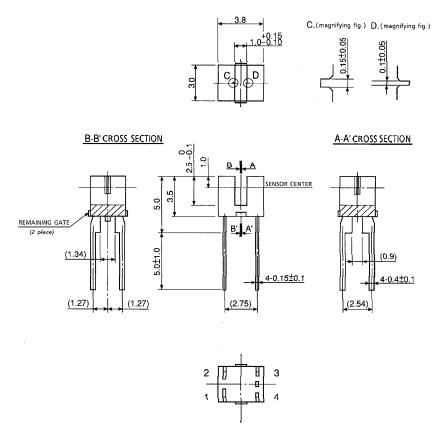
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- Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes are toxic. Do not break, cut or pulverize the product, or use chemicals to dissolve them. When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic garbage.
 The products described in this document are subject to foreign exchange and foreign trade control laws.
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OUTLINE: TOSHIBA

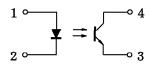
Unit: mm

Tolerance: ± 0.2 mm unless otherwise specified Values in parentheses () are for reference. The remaining gate should be 0.2mm or less.

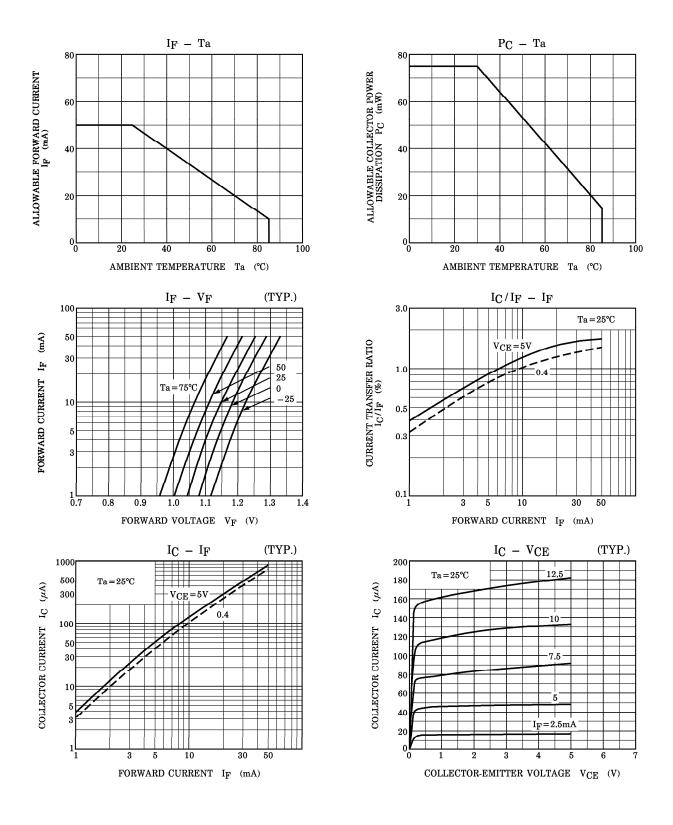


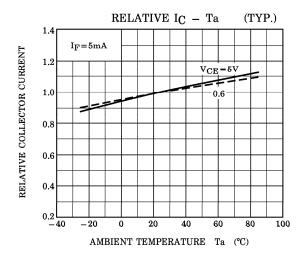
Weight: 0.09g (typ.)

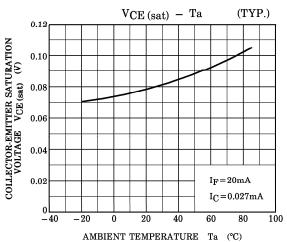
PIN CONNECTION

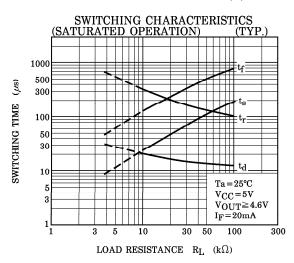


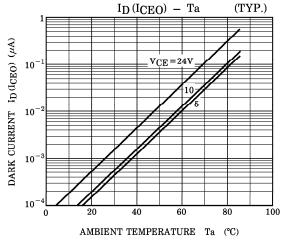
- 1. ANODE
- 2. CATHODE
- 3. EMITTER
- 4. COLLECTOR

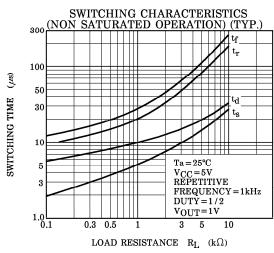


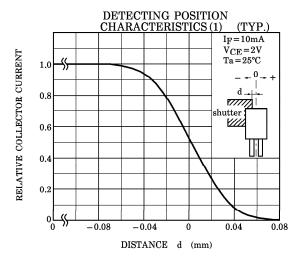


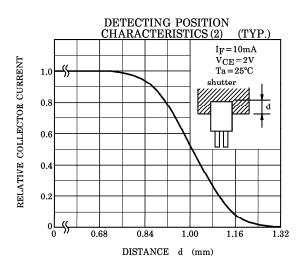












POSITIONING OF SHUTTER AND DEVICE

To operate correctly, make sure that the shutter and the device are positioned as shown in the figure below.

The shit pitch of the shutter must be set wider than the slit width of the device. Determine the width taking the switching time into consideration.

